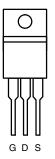




N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)	Q _g (Typ)		
200	0.060 at V _{GS} = 10 V	40	95		
200	0.070 at V _{GS} = 6 V	38.7	95		

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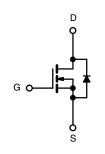


FEATURES

- TrenchFET[®] Power MOSFETS
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

Industrial



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	200	Ň		
Gate-Source Voltage	V _{GS}	± 20	V		
	T _C = 25 °C	1_	40		
Continuous Drain Current ($T_J = 175 \ ^{\circ}C$)	T _C = 125 °C	I _D	23		
Pulsed Drain Current	I _{DM}	70	A		
Avalanche Current		I _{AR}	35	1	
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	61	mJ	
	T _C = 25 °C	P	300 ^b	w	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D –	3.75		
Operating Junction and Storage Temperature R	ange	T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Limit	Unit			
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W			
Junction-to-Case (Drain)	R _{thJC}	0.5	0/00			

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).



SPECIFICATIONS ($T_J = 25$	°C, unless o	otherwise noted)					
Parameter	Symbol	Test Conditions	Min .	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_{D} = 250 \mu A$	200			v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2		4	v	
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 30 V			± 250	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μΑ	
	I _{DSS}	$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			50		
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 V, V_{GS} = 10 V$	70			А	
		V _{GS} = 10 V, I _D = 20 A		0.060			
	Б	V_{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.130		-	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V_{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.170		Ω	
		V _{GS} = 6 V, I _D = 15 A		0.070			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		70		S	
Dynamic ^b	•			•	•		
Input Capacitance	C _{iss}			3000		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		200			
Reverse Transfer Capacitance	C _{rss}			110			
Total Gate Charge ^c	Qg			95	140	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 45 \text{ A}$		28			
Gate-Drain Charge ^c	Q _{gd}			34			
Gate Resistance	Rg	f = 1 MHz		1.6		Ω	
Turn-On Delay Time ^c	t _{d(on)}			22	35		
Rise Time ^c	tr	V _{DD} = 100 V, R _L = 2.78 Ω		220	330		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 45 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 2.5 \Omega$		40	60	ns	
Fall Time ^c	t _f			145	220		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C) ^b		1			
Continuous Current	ا _S				45	•	
Pulsed Current	I _{SM}				70	A	
Forward Voltage ^a	V _{SD}	I _F = 45 A, V _{GS} = 0 V		1	1.5	V	
Reverse Recovery Time	t _{rr}			150	225	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 45 A, di/dt = 100 A/μs		12	18	А	
Reverse Recovery Charge	Q _{rr}			0.9	2	μC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

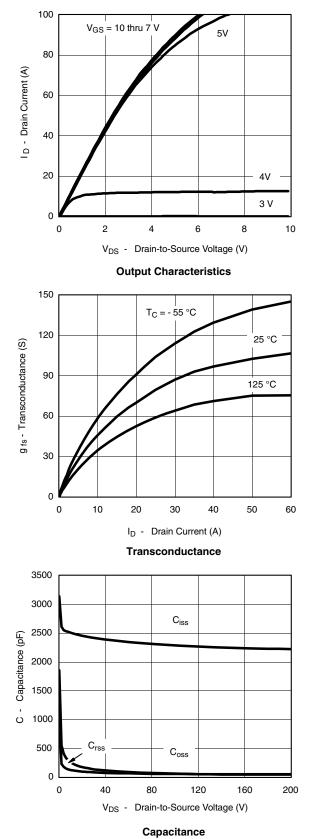
c. Independent of operating temperature.

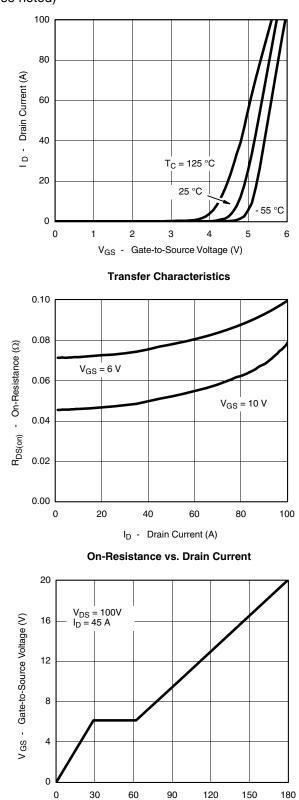
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

emi



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



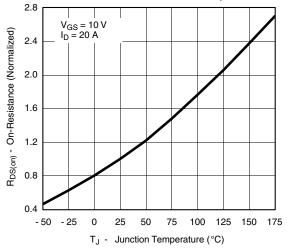


Qg - Total Gate Charge (nC)

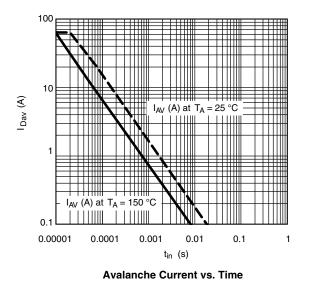
Gate Charge

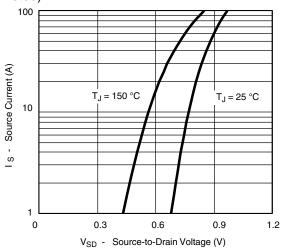


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

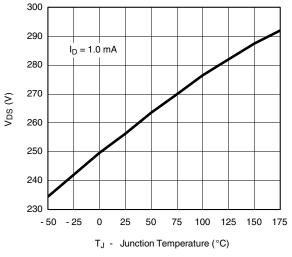


On-Resistance vs. Junction Temperature





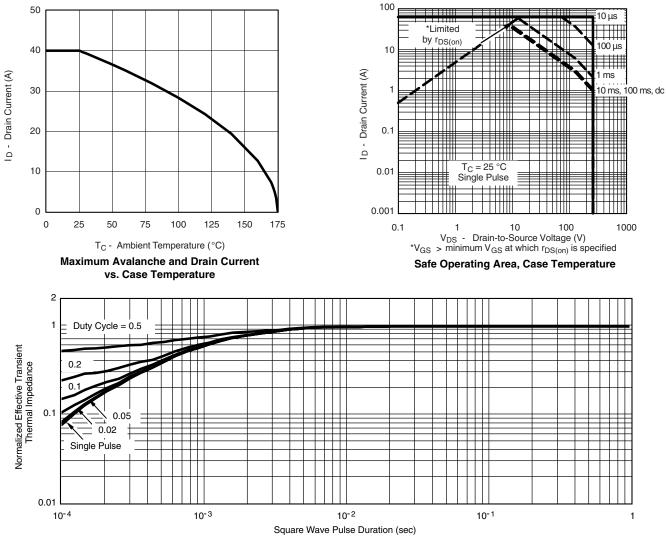
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



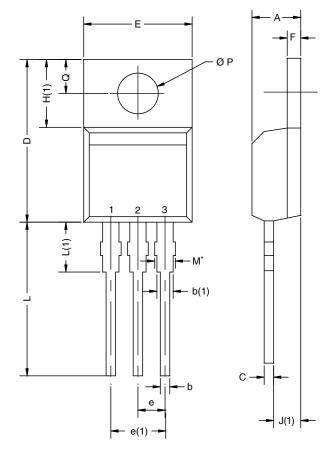
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



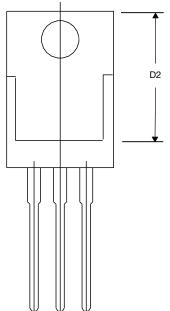
TO-220AB



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





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